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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

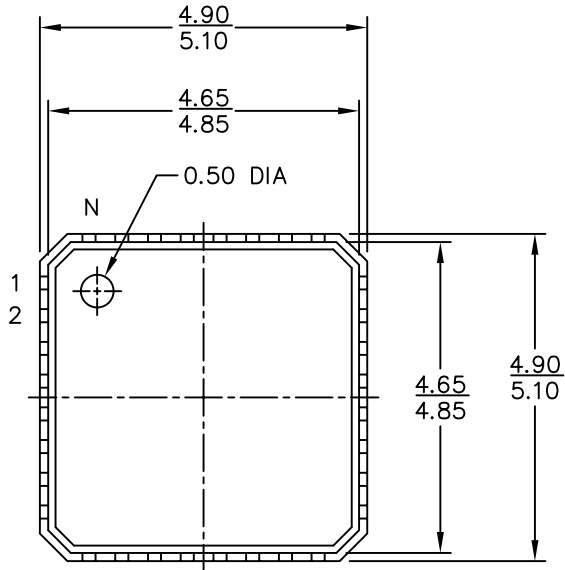
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

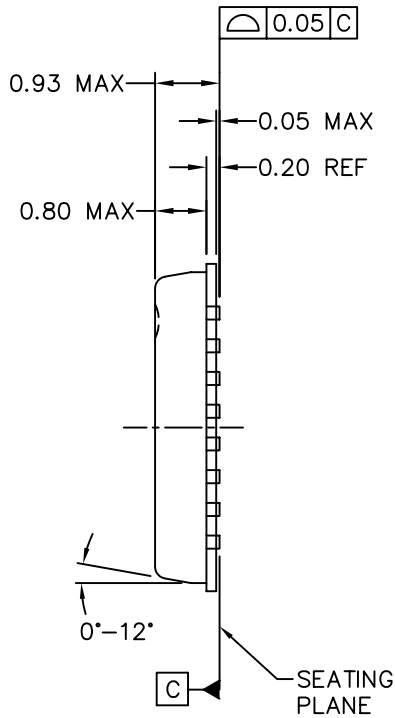
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	127381	NEW RELEASE	06/02/03	N/A
1	-	*A	398665	Added Package Weight, Change Max Package thickness to 0.93mm and added Exposed Pad Dimension.	09/27/05	N/A
1	-	*B	736321	REVISED DRAWING, DEFINED SOLDERABLE EXPOSED PAD CHANGED SPEC. TITLE, CORRECTED EPAD DIMENSION	01/29/07	JSO
1	-	*C	2640207	Corrected EPAD scale from 3.70mm to 3.50 sq	01/19/09	JSO
1	-	*D	2808704	Changed Template and Title from 32LD QFN 5 X 5mm PACKAGE OUTLINE (SUBCON PUNCH TYPE PKG with 3.50 X 3.50 EPAD) to PACKAGE OUTLINE, 32LD QFN 5X5 MM LF32/LY32 3.5X3.5 EPAD (SUBCON PUNCH TYPE PKG)	11/18/09	QAD
1	-	*E	3352919	UPDATE SPECS FOR SUNSET REVIEW. NO CHANGE.	08/24/11	QAD
1	-	*F	3722696	CHANGED PACKAGE WEIGHT FROM "0.054g" TO "REFER TO PMDD SPEC"	08/24/12	QAD

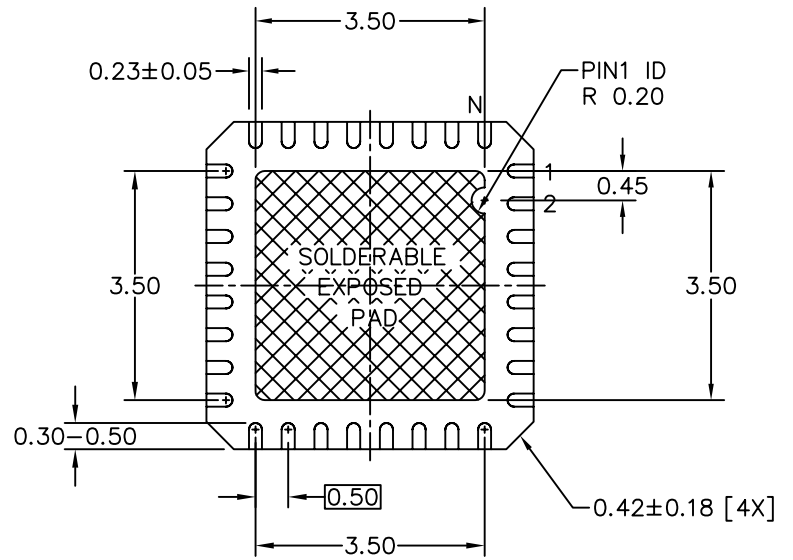
TOP VIEW



SIDE VIEW



BOTTOM VIEW



NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED PAD.
2. REFERENCE JEDEC#: MO-220
3. PACKAGE WEIGHT: REFER TO PMDD SPEC
4. ALL DIMENSIONS ARE IN MM [MIN/MAX]
5. PACKAGE CODE

PART #	DESCRIPTION
LF32	STANDARD
LY32	PB-FREE

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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE:		DESIGNED BY CMG	DATE 11/01/06	CYPRESS Company Confidential
DECIMALS .XX ± 0.05 .XXX ± .XXXX +	ANGLES ± 1°	DRAWN BY CMG	DATE 11/01/06	
MATERIAL N/A	FINISH N/A	CHECKED BY EDCA	DATE 08/24/12	TITLE PACKAGE OUTLINE, 32LD QFN 5X5 MM LF32/LY32 3.5X3.5 EPAD (SUBCON PUNCH TYPE PKG)
		APPROVED BY QAD	DATE 08/24/12	SIZE A
		APPROVED BY ZZQ	DATE 08/24/12	PART NO. LF32/LY32
		APPROVED BY CMG	DATE 08/24/12	DWG NO 51-85188
				REV *F
				SCALED TO FIT N/A
				SHEET 1 OF 1